

# THE PUTTY TF300-3

## Two-Part Low volatile Liquid Gap Filler

TF300 is a two-part 1:1 mixed-curing thermally conductive gel. It can be cured at room temperature. And be cured by heating (80°C) according to customer needs. The thermal conductivity after curing is 3W/mk. The product has good flexibility and is suitable for Dispensing processes in large quantities to improve production efficiency.



### FEATURES / BENEFITS

- Thermal conductivity: 3.0W/m-K
- Curing time adjustable
- Excellent mechanical and chemical stability in wide temperature range
- Low compression force applications

### TYPICAL APPLICATIONS

- Vehicle Electronics
- Fiber Optic Communication Equipment
- SSD
- Network Communication Equipment
- Between Heat Generating Semiconductor and Heat Sink

### HOW TO ORDER

Patron THER PUTTY TF300-3 XXX  
XXX = packaging

### TYPICAL PROPERTIES

Properties	Attribute	Test Method
Color(Part A/B)	White/ Light blue	Visual
Viscosity(mps A/B)	Part A:130 000	ASTM D2196@7# V:15RPM
	Part B:130 000	
Operating time(h,25°C)	1	Operating time: 60 minutes after AB is mixed together, the viscosity change is less than 2 times the initial viscosity.
	24	
Density(g/cc)	3.0	ASTM D792
Hardness after curing(Shore OO )	50	ASTM D2240
Weight Damnify (% , Volatilization, exudation)	≤0.5	@25% /125°C/240H
Usage Temperature (°C)	- 40 to 200	/
Flammability	V-0	UL 94
Shelf Life(month)	6	Temperature <40°C avoid extrusion and exposure to sunlight
<b>Electrical</b>		
Breakdown Voltage (kV/mm)	≥7.0	ASTM D149
Volume Resistivity (Ω.cm)	10 <sup>13</sup>	ASTM D257
Dielectric Constant @1MHz	7.0	ASTM D150
<b>Thermal</b>		
Thermal Conductivity (W/m-K)	3.0	ISO 22007-2